

Experience trends up close!

From E-Mobility to the development of new energy concepts all the way to autonomous driving: Without high-performance dispensing technology and intelligent materials, many of today's trends and mega trends would not have been possible.

For almost 10 years now, the Scheugenpflug TechDays represent know-how, real added value as well as pioneering adhesive bonding, dispensing and potting technology. Once again, we bring together experts from various areas and with their help, you can use these technologies even more successfully. Practice-oriented presentations by specialists in German and English as well as numerous system demonstrations make for a well-rounded event program.

May 10

8:00 Reception & start of the exhibition

Scheugenpflug product portfolio presentation

Sebastian Schmitt, Scheugenpflug AG

9:30 Selection criteria for thermally conductive GapFillers and Adhesives Holger Schuh, THE BERGQUIST COMPANY GmbH a Henkel Company

10:30 New process possibilities by intelligent adhesives Alen Kasner, Martin Böttcher, DELO Industrie Klebstoffe GmbH & Co. KGaA

11:30 Collaborative research in the electronic industry along the whole value chain shown at the example of developing printed circuit boards for high temperatures

Dr. Volker Strubel, InnovationGreen

- Lunch break -

Silicone Coating Materials - Conformal Coating & Selective Coating Materials for enhanced

performance in electronics applications Matthias Grossmann, Momentive Performance Materials GmbH

13:30 Machine availability and service processes (parallel presentation)

Hans-Martin Schall, Scheugenpflug AG Optical Bonding and bonding with silicones 14:30

Dr. Markus Jandke, Wacker Chemie AG 15:30 New epoxy systems with increased thermal conductivity and thermal resistance for

encapsulated windings

Max Poxleitner, WEVO-CHEMIE GmbH Process optimization with new Silicone Adhesives 16:30

May 11

8:00 Reception & start of the exhibition

8:45 Scheugenpflug product portfolio presentation

Sebastian Schmitt, Scheugenpflug AG

9:30 Optical Bonding and bonding with silicones Dr. Markus Jandke, Wacker Chemie AG

Process optimization with new Silicone Adhesives

Florian Damrath, Dow Corning GmbH 11:30 The impact of polymer aging on the reliability of microelectronic systems

Karl-Friedrich Becker, Fraunhofer IZM

- Lunch break -

10:30

New epoxy systems with increased thermal conductivity and thermal resistance for

encapsulated windings

Max Poxleitner, WEVO-CHEMIE GmbH Machine availability and service processes (parallel presentation)

Hans-Martin Schall, Scheugenpflug AG Silicone Coating Materials – Conformal Coating & Selective Coating Materials for

Alen Kasner, Martin Böttcher, DELO Industrie Klebstoffe GmbH & Co. KGaA

enhanced performance in electronics applications

Selection criteria for thermally conductive GapFillers and Adhesives

16:30 New process possibilities by intelligent adhesives

Registration TechDays 2017

Please register via our online form until April 29, 2017:

We are looking forward to meeting you!

Exhibitors:

Material manufacturers:

ACC Silicones Ltd. THE BERGQUIST COMPANY GmbH a Henkel Company

Bluestar Silicones USA Corp

Bodo Möller Chemie GmbH DELO Industrie Klebstoffe GmbH & Co. KGaA

Dow Corning GmbH

ELANTAS Europe GmbH

Electrolube (a division of HK Wentworth Ltd)

HALA Contec GmbH & Co. KG Hermann Otto GmbH (OTTO-CHEMIE)

KERAFOL – Keramische Folien GmbH

LORD Corporation

Momentive Performance Materials GmbH Tyco Electronics Raychem GmbH (a TE Connectivity Ltd. company)

Wacker Chemie AG WEVO-CHEMIE GmbH

Systems suppliers:

CeraCon GmbH **DENSO Robotics Europe** Dr. Hönle AG / Panacol-Elosol GmbH Plasmatreat GmbH

Cluster Mechatronik & Automation e.V.

Media partner: EPP Elektronik Produktion + Prüftechnik

